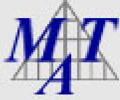

Product Model 6400:
For MCM/Flip Chip/Eutectic and Ultrasonic

MAT – MicroAssembly Technologies, Ltd.
Product Model 6400

Flexible, fully automatic die attach system controlled by user friendly Windows XP® based software.

Model 6400 performs cold and hot processes for MCM, Flip Chip, Eutectic, and Ultrasonic assemblies.

Very high placement accuracy of 3 microns @ 3 sigma (process dependent) is ensured
by the closed loop servo systems and the high resolution digital vision system

Handles active and passive components with sizes between 200 microns up to over 25 mm.

Pick from up to thirty 2" or nine 4" Waffle or Gel packs.

Pick from Wafers up to 300 mm

Pick from up to 8 Tape & Reel feeders.

Specializing in unusual die sizes and aspect ratios.

The volumetric dispenser applies adhesive in programmable shapes.

Stamping (Pin Transfer) applies adhesive dots as small as 75 microns.

Full Flip Chip capability including chip flipping, bump fluxing and chip final alignment over up looking camera.

Handles CCD and other sensors, LCD's, MEMS and other sensitive devices

Unique die staking capability.